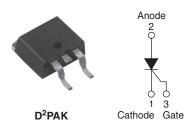


Vishay Semiconductors

Surface Mountable Phase Control SCR, 16 A



| PRODUCT SUMMARY | | | | | |
|------------------------|-----------------|--|--|--|--|
| V _T at 16 A | < 1.25 V | | | | |
| I _{TSM} | 300 A | | | | |
| V _{RRM} | 800 V to 1600 V | | | | |

FEATURES

- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Compliant to RoHS directive 2002/95/EC
- Halogen-free according to IEC 61249-2-21 definition
- Designed and qualified for industrial level

APPLICATIONS

- Input rectification (soft start)
- Vishay input diodes, switches and output rectifiers which are available in identical package outlines

DESCRIPTION

The VS-25TTS...SPbF High Voltage Series of silicon controlled rectifiers are specifically designed for medium power switching and phase control applications. The glass passivation technology used has reliable operation up to 125 °C junction temperature.

| OUTPUT CURRENT IN TYPICAL APPLICATIONS | | | | | | | | |
|---|--|------|---|--|--|--|--|--|
| APPLICATIONS | SINGLE-PHASE BRIDGE THREE-PHASE BRIDGE UNITS | | | | | | | |
| NEMA FR-4 or G10 glass fabric-based epoxy with 4 oz. (140 $\mu m)$ copper | 3.5 | 5.5 | | | | | | |
| Aluminum IMS, R _{thCA} = 15 °C/W | 8.5 | 13.5 | A | | | | | |
| Aluminum IMS with heatsink, $R_{thCA} = 5 \text{ °C/W}$ | 16.5 | 25.0 | | | | | | |

Note

• $T_A = 55 \text{ °C}, T_J = 125 \text{ °C}, \text{ footprint } 300 \text{ mm}^2$

| MAJOR RATINGS AND CHARACTERISTICS | | | | | | | | |
|------------------------------------|------------------------------|-------------|-------|--|--|--|--|--|
| PARAMETER | TEST CONDITIONS | VALUES | UNITS | | | | | |
| I _{T(AV)} | Sinusoidal waveform | 16 | ٨ | | | | | |
| I _{RMS} | | 25 | A | | | | | |
| V _{RRM} /V _{DRM} | | 800 to 1600 | V | | | | | |
| I _{TSM} | | 300 | A | | | | | |
| V _T | 16 A, T _J = 25 °C | 1.25 | V | | | | | |
| dV/dt | | 500 | V/µs | | | | | |
| dl/dt | | 150 | A/µs | | | | | |
| TJ | | - 40 to 125 | °C | | | | | |

| VOLTAGE RATINGS | | | | | | | | |
|-----------------|---|--|---|--|--|--|--|--|
| PART NUMBER | V _{RRM} , MAXIMUM PEAK REVERSE VOLTAGE V | V _{DRM} , MAXIMUM PEAK DIRECT VOLTAGE V | I _{RRM} /I _{DRM} , AT 125 °C mA | | | | | |
| VS-25TTS08SPbF | 800 | 800 | | | | | | |
| VS-25TTS12SPbF | 1200 | 1200 | 10 | | | | | |
| VS-25TTS16SPbF | 1600 | 1600 | | | | | | |



FREE

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| ABSOLUTE MAXIMUM RATINGS | | | | | | |
|--|----------------------------------|---|---|-----|--------|------------------|
| PABAMETER | SYMBOL | TEST CONDITIONS | | | VALUES | |
| PARAMETER | STNIDUL | IES | TEST CONDITIONS | | | UNITS |
| Maximum average on-state current | I _{T(AV)} | T _C = 93 °C, 180° d | conduction half sine wave | 16 | | |
| Maximum RMS on-state current | I _{RMS} | | | 2 | 5 | А |
| Maximum peak, one-cycle, | less s | 10 ms sine pulse, | rated V _{RRM} applied | 30 | 00 | ~ |
| non-repetitive surge current | I _{TSM} | 10 ms sine pulse, | no voltage reapplied | 3 | 50 | 1 |
| Maximum I ² t for fusing | l ² t | 10 ms sine pulse, | rated V _{RRM} applied | 4 | 50 | A ² s |
| | 1-1 | 10 ms sine pulse, | no voltage reapplied | 630 | | A-2 |
| Maximum I ² \sqrt{t} for fusing | l²√t | t = 0.1 ms to 10 ms, no voltage reapplied | | | 00 | A²√s |
| Maximum on-state voltage drop | V _{TM} | 16 A, T _J = 25 °C | | | 25 | V |
| On-state slope resistance | r _t | T ₁ = 125 °C | | | 2.0 | mΩ |
| Threshold voltage | V _{T(TO)} | $1_{j} = 125 C$ | | | .0 | V |
| Maximum reverse and direct leakage current | 1 /1 | T _J = 25 °C | V _B = Rated V _{BBM} /V _{DBM} | 0.5 | | |
| Maximum reverse and direct leakage current | I _{RM} /I _{DM} | T _J = 125 °C | VR - Haleu VRRM/ VDRM | 1 | 0 | |
| Holding current | Ι _Η | VS-25TTS08, VS-25TTS12 | Anode supply = 6 V, | - | 100 | mA |
| C C C C C C C C C C C C C C C C C C C | | VS-25TTS16 | resistive load, initial I _T = 1 A | 100 | 150 | |
| Maximum latching current | ١L | Anode supply = 6 V, resistive load | | 200 | | |
| Maximum rate of rise of off-state voltage | dV/dt | | | 50 | 00 | V/µs |
| Maximum rate of rise of turned-on current | dl/dt | | | 1: | 50 | A/µs |

| TRIGGERING | | | | | |
|---|--------------------|--|--------|-------|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | VALUES | UNITS | |
| Maximum peak gate power | P _{GM} | | 8.0 | W | |
| Maximum average gate power | P _{G(AV)} | | 2.0 | vv | |
| Maximum peak positive gate current | + I _{GM} | | 1.5 | А | |
| Maximum peak negative gate voltage | - V _{GM} | | 10 | V | |
| | I _{GT} | Anode supply = 6 V, resistive load, T_J = - 10 °C | 60 | | |
| Maximum required DC gate current to trigger | | Anode supply = 6 V, resistive load, $T_J = 25 \text{ °C}$ | 45 | mA | |
| | | Anode supply = 6 V, resistive load, $T_J = 125 \text{ °C}$ | 20 | | |
| | | Anode supply = 6 V, resistive load, T_J = - 10 °C | 2.5 | | |
| Maximum required DC gate voltage to trigger | V _{GT} | Anode supply = 6 V, resistive load, $T_J = 25 \text{ °C}$ | 2.0 | v | |
| | | Anode supply = 6 V, resistive load, $T_J = 125 \text{ °C}$ | 1.0 | v | |
| Maximum DC gate voltage not to trigger | V_{GD} | T 105 °C V Deted volve | 0.25 | | |
| Maximum DC gate current not to trigger | I _{GD} | $T_J = 125 \text{ °C}, V_{DRM} = \text{Rated value}$ | | mA | |

| SWITCHING | | | | | | | |
|-------------------------------|-----------------|--------------------------|--------|-------|--|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | VALUES | UNITS | | | |
| Typical turn-on time | t _{gt} | T _J = 25 °C | 0.9 | | | | |
| Typical reverse recovery time | t _{rr} | T _{.1} = 125 °C | 4 | μs | | | |
| Typical turn-off time | t _q | 1j = 125 C | 110 | | | | |





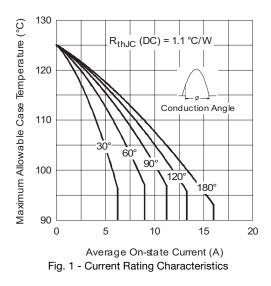
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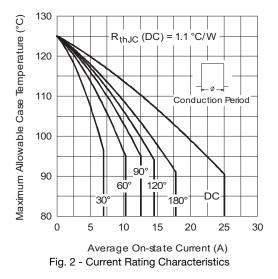
| THERMAL AND MECHANICAL SPECIFICATIONS | | | | | | | |
|--|-----------------------------------|---|-------------|-------|--|--|--|
| PARAMETER | SYMBOL | SYMBOL TEST CONDITIONS | | UNITS | | | |
| Maximum junction and storage temperature range | T _J , T _{Stg} | | - 40 to 125 | °C | | | |
| Soldering temperature | Τ _S | For 10 s (1.6 mm from case) | 240 | | | | |
| Maximum thermal resistance, junction to case | R _{thJC} | DC operation | 1.1 | °C/W | | | |
| Typical thermal resistance, junction to ambient (PCB mount) | R _{thJA} ⁽¹⁾ | | 40 | 0/10 | | | |
| Approximate weight | | | 2 | g | | | |
| Approximate weight | | | 0.07 | oz. | | | |
| | | | 25TT | S08S | | | |
| Marking device | | Case style D ² PAK (SMD-220) | 25TT | S12S | | | |
| | | | 25TT | S16S | | | |

Note

⁽¹⁾ When mounted on 1" square (650 mm²) PCB of FR-4 or G-10 material 4 oz. (140 μm] copper 40 °C/W

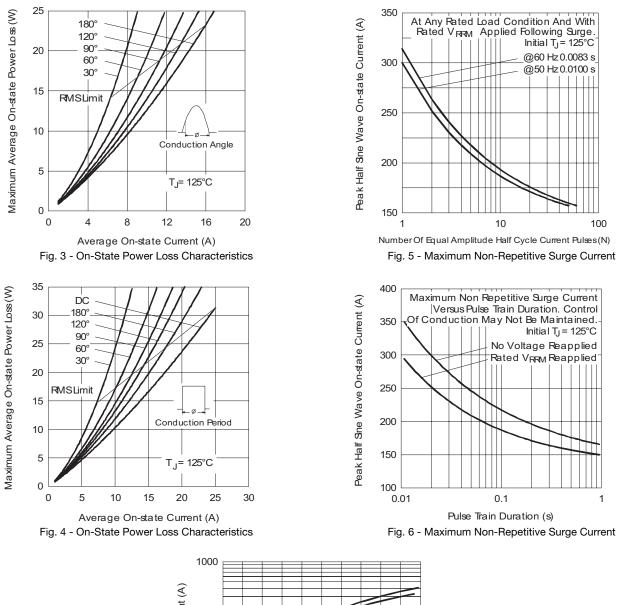
For recommended footprint and soldering techniques refer to application note #AN-994

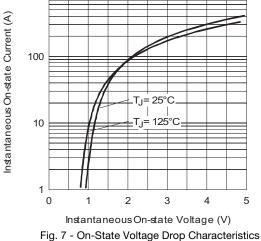




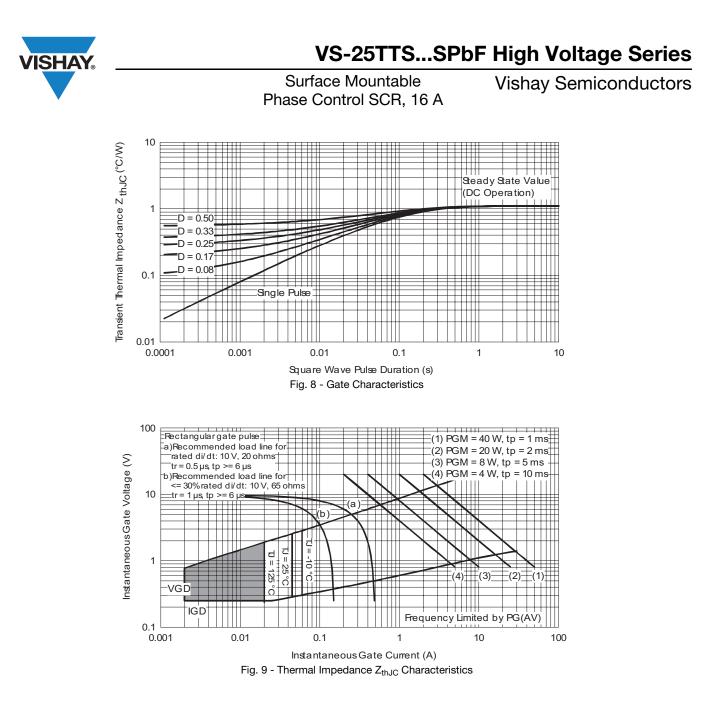
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Vishay Semiconductors

Surface Mountable Phase Control SCR, 16 A

ORDERING INFORMATION TABLE

| Device code | VS- | 25 | т | т | S | 12 | S | TRL | PbF | |
|-------------|-----|--------|------------|--------------------|-----------|-----------|--------------------|------|--------|----|
| | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | |
| | 1 . | - HPI | ⊃ produ | ct suffix | | | | | | |
| | 2 | Cur | rent rati | ng (25 = | 25 A) | | | | | |
| | 3 - | - Circ | uit conf | iguratior | ו: | | | | | |
| | | T = | Single t | hyristor | | | | | | |
| | 4 | - Pac | kage: | | | | | | | |
| | | T = | TO-220 | AC | | | | | | |
| | 5 - | - Тур | e of silio | con: | | | | | | |
| | | S = | Standa | rd recov | ery rect | lifier | | | 08 = 8 | 3(|
| | 6 | - Volt | tage rati | ng: Volt | age cod | le x 100 | = V _{RRI} | и —— | 12 = 1 | 2 |
| | 7 - | - S = | TO-220 | D ² PAK | (SMD- | 220) ve | rsion | | 16 = 1 | 6 |
| | 8 - | • No | one = Tu | ıbe | | | | | | |
| | | • TF | RL = Tap | e and re | eel (left | orienteo | d) | | | |
| | | • TF | RR = Ta | pe and r | eel (rigł | nt orient | ed) | | | |
| | 9. | · PbF | = Lead | l (Pb)-fre | ee | | | | | |

| LINKS TO RELATED DOCUMENTS | | | | | |
|-------------------------------------|--------------------------|--|--|--|--|
| Dimensions www.vishay.com/doc?95046 | | | | | |
| Part marking information | www.vishay.com/doc?95054 | | | | |
| Packaging information | www.vishay.com/doc?95032 | | | | |



Vishay

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